

BOX HEADER, 2.0MM PITCH, SMT TYPE.

1. SCOPE

This specification covers performance, tests and quality requirements for **BOX HEADER, 2.0MM PITCH, SMT TYPE.**

2. APPLICABLE DOCUMENT

The following documents form a part of this specification to the extent specified herein. In the event of conflict between the requirements of this specification and the product drawing, the product drawing shall take precedence. In the event of conflict between the requirements of this specification and the referenced documents, this specification shall take precedence.

Test Report : 501-57265 REV.O

3. REQUIREMENTS

3.1. DESIGN AND CONSTRUCTION

Product shall be of the design, construction and physical dimensions specified on the applicable product drawing.

3.2. MATERIALS

- A. Housing: Thermoplastic, UL94V-0.
- B. Contact: Copper Alloy, Gold plating on contact area, Tin-lead plated on soldertails, Nickel underplated all over.

3.3. RATINGS

- A. Current Rating: 1 A Max.
- B. Voltage Rating: 250 VAC Max.
- C. Operating temperature: -40°C to +105°C.

3.4. TEST CONDITION

The product is designed to meet the electrical, mechanical and environmental performance requirements specified in Figure 1.

DR	DATE	CHK	DATE	APVD	DATE
Oblic Hu	16-Aug-2002	Jerry Cheng	16-Aug-2002	Jebb Wu	16-Aug-2002

FZ00-0179-02

3.5. TEST REQUIREMENTS AND PROCEDURES SUMMARY

TEST DESCRIPTION	REQUIREMENT	PROCEDURED
Examination of product	Meets requirements of product drawing and AMP Specification.	Visual inspection No physical damage
ELECTRICAL		
Contact Resistance	20mΩ Max Initial 30mΩ Max Final	EIA-RS-364-06A
Insulation Resistance	5000MΩ Min.Initial	EIA-364-21B. Apply 500VDC for 1 minute.
Dielectric Withstanding Voltage	No evidence of break-down and flashes	500V AC rms, for 1 minutes applied between Adjacent contacts. EIA-364-20A.Method B.
MECHANICAL		
Mating Force	200g Max. per pin.	EIA- 364-13
Unmating Force	20g Min. per pin.	EIA- 364-13
Contact Retention Force	350gf Min Per Contact	Pull connectors at maximum rate of 25mm per minute
Vibration	No electrical discontinuity greater Than 1 microseconds shall occur	EIA-364-28 Test condition I, 10-55-10 Hz/min. Amplitude: 1.52mm,Period: 2 hours for each direction X.Y.Z axis.
ENVIRONMENTAL		
Humidity-Cycling Test	See Note , 30mΩ Max .Final	At a temperature of 40°C± 2°C and relative humidity of 90~95% for 96 hours. EIA-364-31A, method II, condition A.
Salt Spray	See Note , 30mΩ Max .Final	Exposing in a heat chamber at a temperature of 35°C± 2°C for 24 hours. EIA-364-26A, condition A.
Thermal Shock	See Note	5 cycles between +85°C/30minutes and -55°C /30minutes. EIA-364-32B, condition I.
Temperature Life	See Note , 30mΩ Max .Final	Temperature 105± 3°C for 250 hours. EIA-364-17A, method A, condition 4.
PHYSICAL		
Solder ability	95% Min. See Note	Temperature 245± 5°C, 4~5sec. EIA-364-52
Resistance to Soldering heat	See Note	Specimen shall be mounted on PCB 260± 5°C 10± 1sec. MIL-STD-202F, Method 208C.

Figure 1

NOTE: Shall meet visual requirements, show no physical damages.

3.6. PRODUCT QUALIFICATION AND REQUALIFICATION TEST SEQUENCE

Test or Examination	Test Group							
	A	B	C	D	E	F	G	H
	Test Sequence (a)							
Examination of Product	1,5	1,7	1,3	1,5	1,3	1,5	1,7	1,5
Contact Resistance	2,4	2,6		2,4		2,4	2,6	2,4
Insulation Resistance								
Dielectric Withstanding Voltage		3,5						
Mating Force							3	
Unmating Force							4	
Contact Retention Force							5	
Vibration								3
Humidity		4						
Resistance to solder heat						3		
Salt Spray			2					
Thermal Shock	3							
Temperature Life				3				
Solderability					2			

Figure 2

NOTE : (a) Numbers indicate sequence in which tests are performed.